

Title (en)

Chemical mechanical polishing aqueous dispersion, chemical mechanical polishing method, and kit for preparing chemical mechanical polishing aqueous dispersion

Title (de)

Wässrige Dispersion für chemisch-mechanisches Polieren, chemisch-mechanisches Polierverfahren und Kit zur Zubereitung einer wässrigen Dispersion für chemisch-mechanisches Polieren

Title (fr)

Dispersion aqueuse par polissage chimico-mécanique, méthode de polissage chimico-mécanique et kit de préparation de la dispersion aqueuse par polissage chimico-mécanique

Publication

EP 1724317 A1 20061122 (EN)

Application

EP 06113995 A 20060516

Priority

JP 2005143580 A 20050517

Abstract (en)

A chemical mechanical polishing aqueous dispersion, including: (A) inorganic particles; (B) at least one type of particles selected from the group consisting of organic particles and organic-inorganic composite particles; (C) at least one compound selected from the group consisting of quinolinecarboxylic acid, quinolinic acid, a divalent organic acid (excluding quinolinic acid), and a hydroxyl acid; (D) at least one compound selected from the group consisting of benzotriazole and benzotriazole derivatives; (E) an oxidizing agent; and (F) water, the chemical mechanical polishing aqueous dispersion containing the component (A) in an amount of 0.05 to 2.0 wt% and the component (B) in an amount of 0.005 to 1.5 wt%, having a ratio (W A /W B) of the amount (W A) of the component (A) to the amount (W B) of the component (B) of 0.1 to 200, and having a pH of 1.0 to 5.0.

IPC 8 full level

C09G 1/02 (2006.01); **C09K 3/14** (2006.01); **H01L 21/321** (2006.01)

CPC (source: EP KR US)

C09G 1/02 (2013.01 - EP US); **C09K 3/1463** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR); **H01L 21/3212** (2013.01 - EP US)

Citation (search report)

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EP2017318A3; KR101469994B1; CN101469252A; EP2794733A4; US8470195B2

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KR 20060119774 A 20061124; TW 200700545 A 20070101; US 2006276041 A1 20061207

DOCDB simple family (application)

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